ASSOCIATION CONNECT ELECTRONICS INDUSTR	Material Composi © Copyright 2005. IPC, international and Pan-Ai	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					als and M	Ifg Informat	ion		
upplier Infor									,						
Company name*			Company unique ID			Unique II	Unique ID Authority					Response Date*			
nsemi												2024-04-23			
Contact Name			Title - Contact			Phone - 0	Phone - Contact*					Email - Contact*			
Product-Env-Stev	wards		Product Enviro Compliance			NA	NA				Product-Env-Stewards@onsemi.com				
uthorized Repre	sentative*		Title - Representative			Phone - I	Phone - Representative*				Email - Representative*				
Product-Env-Stev	wards		Product Enviro Compliance			NA	NA				Product-Env-Stewards@onsemi.com				
Reques	Requester Item Number Mfn		Ifr Item Number Mfr Item Name			Effective	e Date	Version	Version Manufacturing Site			Weight*	UOM	Unit Type	
		N01S830HAT22ET AU		AUTOMOTIVE, 1MB 3.V hold fnc, TSSOP		P 2024-04	-23		Т	TH6		32.92	mg	Each	
	g Proccess Information								•						
8			,		I-STD-020 MSL Rating				Body Temperature   Max Time at Peak		Temperat	ture Numl	ber of Reflow Cyc	les	
Matte 7	Γin (Sn) - annealed	C	U Alloy	3	3	260		[(	2	30	secon	nds 3			
omments															
	SL 3 Rated item requires Ba		`												
or more informa	tion regarding material con	nposition p	olease refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure it accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have not written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.65	mg	Supplier	oplier Silicon (Si)			1.65	mg
Die Attach	0.9	mg	Supplier	Epoxized Condensate Of Para- Hydrobenzaldehyde And Alkyl Phenol	129915-35-1		0.18	mg
			Supplier	Silver (Ag)	7440-22-4		0.72	mg
Lead Frame	10.6	mg	Supplier	Magnesium (Mg)	7439-95-4		0.0159	mg
			Supplier	Silicon (Si)	7440-21-3		0.0689	mg
			В	Nickel (Ni)	7440-02-0		0.318	mg
			Supplier	Copper (Cu)	7440-50-8		10.1972	mg
Mold Compound-Black	19.11	mg		Epoxy Phenol Resin	proprietary data		2.6754	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		16.4346	mg
Plating	0.44	mg	Supplier	Tin (Sn)	7440-31-5		0.44	mg
Wire Bond - Au	0.22	mg	Supplier	Gold (Au)	7440-57-5		0.22	mg